USB3.0 MICRO-B UPSTREAM CONNECTOR

These connections are for flow through routing.

Keep ESD close to connector.

Keep caps close to connector.

Intentionally swapped polarity.

USB3.0 MICRO B CONNECTOR

VBUS_PUP_FB
SSTXP_PUP
SSTXM_PUP
SSRXM_UP
SSRXM_UP

Route these lines on the top side only.
USB POWER DELIVERY

PORTS 1 & 2

PORT 3

PORT 4

ACTIVE HIGH ENABLE:
8041 HAS INTERNAL FULL-DOWNS
THESE RESISTORS ENABLE
BATTERY CHARGING ON
PORTS 1 AND 2

FIXED CURRENT LIMIT OUTPUT OF 2A

PORTS 3 AND 4

USB IN [P2,3,7,8]

VBUS OUT [P1,2,3,4]
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